



## Convective Heat and Mass Transfer of Nanofluids

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### Message from the Guest Editors

Nanofluids are an emerging new heat transfer media in which nanometer-sized particles are suspended in conventional fluids. The improved properties open up a wide range of applications, such as convective heat and mass transfer. Depending on its shape and concentration, nanoparticles in the fluid also exhibit non-Newtonian behavior, which substantially affects the resultant convective current and its associated heat and mass transfer performance.

The above information only exemplifies a few physical phenomena involved in nanofluid applications. Although much research efforts have been made to elucidate the underlaid physical mechanism, there are still many inconsistent theories and conspicuous hypothesis unanswered. This Special Issue is developed to collect and showcase the current state-of-the-art of nanofluids and their applications. Because of the complex behavior of nanofluids, fundamental, applied studies in nanofluids, thermal-physical properties, rheological characterization and electrochemically active nanofluidics, are welcome. Papers that focus on the expansion of nanofluid applications in diverse, multidisciplinary research are also welcome.





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## Message from the Editor-in-Chief

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